

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC084P03NS3E G	**Issued**	12. May 2021
MA#	MA001701968		
Package	PG-TDSON-8-40	**Weight***	112.36 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.835	1.63	1.63	16330	16330
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		130	
	non noble metal	iron	7439-89-6	0.049	0.04		434	
	non noble metal	copper	7440-50-8	48.649	43.32	43.37	432968	433532
wire	non noble metal	copper	7440-50-8	0.058	0.05	0.05	513	513
encapsulation	organic material	carbon black	1333-86-4	0.083	0.07		735	
	plastics	epoxy resin	-	6.526	5.81		58083	
	inorganic material	silicondioxide	60676-86-0	34.697	30.88	36.76	308798	367616
leadfinish	non noble metal	tin	7440-31-5	1.520	1.35	1.35	13528	13528
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1410	1410
solder	non noble metal	tin	7440-31-5	0.037	0.03		328	
	noble metal	silver	7440-22-4	0.046	0.04		409	
	non noble metal	lead	7439-92-1	1.758	1.56	1.63	15642	16379
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.02		151	
	non noble metal	copper	7440-50-8	16.910	15.05	15.07	150496	150692
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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